Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138

Manufacturing Bulletin

Subject: Shipping Container Change – Tray Shipment
(Revised to add BGA and FCBGA and to clarify the affected package list*)

Date: September 12, 2006

Integrated Device Technology, Inc. will introduce a smaller shipping box for products shipped in trays as listed in the attachment. The purpose of this change is to improve the storage space. There is no change in the standard or custom shipping labels, number of tray per stack and quantity per tray. The end caps are retained and will now have a cushion ring for added protection. This new shipping box has been tested and meets ASTM D5276-98, Standard Test Method for Drop Test of Loaded Containers by Free Fall.

During the transition period, customers may receive shipments in either box type.

Yours sincerely,

PS Tow
Director, Product QA
Integrated Device Technology, Inc.
PSTow@idt.com
Tel. # (408) 284-8206

Integrated Device Technology, Inc.
6024 Silver Creek Valley Road
San Jose, CA 95138

Manufacturing Bulletin

ATTACHMENT

Subject: Shipping Container Change – Tray Shipment
Date: September 12, 2006

AFFECTED PACKAGE LIST:
BGA*, FCBGA*, TQFP, PQFP (except 28mm x 28mm*), VQFP-N and TSOP

	EXISTING BOX	**NEW BOX**
Dimension	402 x 202 x 96 mm	368 x 169 x 56 mm
Details	4+1 per bundle	4+1 per bundle
	PP-strap (4+1)	PP-strap (4+1)
	End-cap	End-cap
	Desiccant (2 units) & HIC *	Desiccant (2 units) & HIC *
	Moisture Barrier Bag *	Moisture Barrier Bag *
	Paper cap	Cushion ring

* These are required only for moisture sensitive (MSL 3) products.

Photos

Existing Box

New Box

The above example is the dry pack method for MSL 3 products. Non-moisture sensitive (MSL1) products do not require dry packing.